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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	e200z7
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CANbus, SCI, SPI
Peripherals	DMA, POR, PWM
Number of I/O	32
Program Memory Size	3MB (3M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192K x 8
Voltage - Supply (Vcc/Vdd)	1.08V ~ 5.25V
Data Converters	A/D 64x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	416-BBGA
Supplier Device Package	416-PBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/spc5673fk0mvr2r

	1	2	3	4	5	6	7	8	9	10	11	
A	VSS	VDD	RSTOUT	ANA0	ANA1	ANA4	ANA5	ANA15	VDDA_A0	VRH_A	VRL_A	A
B	VDDEH1	VSS	VDD	TEST	ANA2	ANA3	ANA6	ANA7	VDDA_A0	VSSA_A1	REF-BYPCA	B
C	ETPUA21	ETPUA26	VSS	VDD	ANA8	ANA10	ANA9	ANA13	ANA17	ANA19	ANA21	C
D	ETPUA23	ETPUA25	ETPUA31	VSS	VDD	ANA11	ANA12	ANA14	ANA16	ANA18	ANA20	D
E	ETPUA20	ETPUA22	ETPUA24	ETPUA30								
F	ETPUA13	ETPUA14	ETPUA15	ETPUA27								
G	ETPUA10	ETPUA11	ETPUA12	ETPUA17								
H	ETPUA5	ETPUA6	ETPUA9	ETPUA16								
J	ETPUA1	ETPUA2	ETPUA3	ETPUA4					VSS	VSS	VSS	J
K	TCRCLKA	ETPUA0	VDD	VSTBY					VSS	VSS	VSS	K
L	BOOT-CFG1	PLLCFG1	PLLCFG2	VDDEH1					VSS	VSS	VSS	L
M	JCOMP	RESET	PLLCFG0	RDY					VDDE2	VSS	VSS	M
N	VDDE2	MCKO	MSEO1	EVTI					VDDE2	VDDE2	VSS	N
P	EVTO	MSE00	MDO0	MDO1					VDDE2	VDDE2	VSS	P
R	MDO2	MDO3	MDO4	MDO5								
T	MDO6	MDO7	MDO8	VDDE2								
U	MDO9	MDO10	MDO11	MDO15								
V	MDO12	VDDE2	MDO14	VDD33_2								
W	TDO	MDO13	TMS	VSS	VDD	VDDE2	PCSB2	VDDEH4	VDD	EMIOS8	EMIOS9	W
Y	TCK	TDI	VSS	VDD	FR_A_TX	FR_B_TX	SCKA	SCKB	PCSB0	EMIOS2	EMIOS5	Y
AA	ENGCLK	VSS	VDD	FR_A_RX	FR_B_RX	PCSA5	SINA	SINB	EMIOS0	EMIOS3	EMIOS10	AA
AB	VSS	VDD	FR_A_TX_EN	VDDE2	FR_B_TX_EN	PCSA0	SOUTA	SOUTB	EMIOS1	EMIOS4	EMIOS7	AB
	1	2	3	4	5	6	7	8	9	10	11	

Figure 4. MPC5674F 324-ball TEPBGA (1 of 2)

Pin Assignments

	12	13	14	15	16	17	18	19	20	21	22	
A	REF-BYPCB1	VDDA_B0	REF-BYPCB1	VRL_B	VRH_B	ANB2	ANB3	ANB6	ANB7	ANB22	VSS	A
B	REF-BYPCB	VDDA_B1	VSSA_B0	ANB0	ANB1	ANB4	ANB5	ANB19	ANB23	VSS	TCRCLKC	B
C	ANA23	ANB10	ANB9	ANB11	ANB12	ANB14	ANB16	ANB20	VSS	ETPUC0	VDDEH7	C
D	ANA22	ANB8	ANB13	ANB15	ANB17	ANB18	ANB21	VSS	ETPUC1	ETPUC3	ETPUC2	D
									ETPUC5	ETPUC10	ETPUC11	ETPUC4
									ETPUC12	ETPUC14	ETPUC13	ETPUC9
									ETPUC20	ETPUC18	ETPUC19	ETPUC17
									VDDEH7	ETPUC23	ETPUC22	ETPUC21
J	VSS	VSS	VSS						ETPUC27	ETPUC28	ETPUC26	ETPUC24
K	VSS	VSS	VSS						ETPUC31	ETPUC30	ETPUC29	ETPUC25
L	VSS	VSS	VSS						ETPUB12	ETPUB13	ETPUB14	VDDEH7
M	VSS	VSS	VSS						ETPUB7	ETPUB10	ETPUB11	ETPUB9
N	VSS	VSS	VSS						ETPUB0	VDDEH6	ETPUB8	ETPUB6
P	VSS	VSS	VSS						TCRCLKB	ETPUB16	ETPUB5	ETPUB4
									ETPUB1	ETPUB17	ETPUB3	ETPUB2
									ETPUB19	ETPUB18	VDDEH6	REGCTL
									ETPUB31	ETPUB30	VDDREG	VSSSYN
									VDD	REGSEL	VSSFL	EXTAL
W	EMIOS18	EMIOS22	EMIOS27	EMIOS31	CNTXC	CNRXC	CNRXB	VSS	VDD	VDD33_3	XTAL	W
Y	EMIOS14	EMIOS15	EMIOS19	EMIOS23	EMIOS26	EMIOS30	CNTXB	CNRXD	VSS	VDD	VDDSYN	Y
AA	EMIOS13	EMIOS17	EMIOS21	EMIOS25	EMIOS28	EMIOS29	CNRXA	SCKC	SINC	VSS	VDD	AA
AB	EMIOS11	EMIOS12	EMIOS16	EMIOS20	EMIOS24	CNTXA	SOUTC	PCSC0	VDDEH4	CNTXD	VSS	AB
	12	13	14	15	16	17	18	19	20	21	22	

Figure 5. MPC5674F 324-ball TEPBGA (2 of 2)

Pin Assignments

	1	2	3	4	5	6	7	8	9	10	11	12	13	
A	VSS	VDD	RSTOUT	ANA0	ANA4	ANA8	ANA11	ANA15	VDDA_A0	REFBYP-CA1	VRL_A	VRH_A	AN28	A
B	VDDEH1	VSS	VDD	TEST	ANA1	ANA5	ANA10	ANA14	VDDA_A1	VSSA_A1	REFBYPICA	AN24	AN27	B
C	ETPUA30	ETPUA31	VSS	VDD	ANA2	ANA6	ANA9	ANA13	ANA17	ANA19	ANA21	ANA23	AN26	C
D	ETPUA27	ETPUA28	ETPUA29	VSS	VDD	ANA3	ANA7	ANA12	ANA16	ANA18	ANA20	ANA22	AN25	D
E	ETPUA23	ETPUA24	ETPUA25	ETPUA26										E
F	ETPUA19	ETPUA20	ETPUA21	ETPUA22										F
G	ETPUA15	ETPUA16	ETPUA17	ETPUA18										G
H	ETPUA11	ETPUA12	ETPUA14	ETPUA13										H
J	ETPUA7	ETPUA8	ETPUA9	ETPUA10										J
K	ETPUA3	ETPUA4	ETPUA5	ETPUA6										K
L	TCRCLKA	ETPUA0	ETPUA1	ETPUA2										L
M	VDD33_1	TXDA	RXDA	VSTBY										M
N	RXDB	BOOTCFG1	WKPCFG	VDD						VDDE2	VSS	VSS	VSS	N
	1	2	3	4	5	6	7	8	9	10	11	12	13	

Figure 7. MPC5674F 416-ball TEPBGA (1 of 4)

MPC5674F 416-ball TEPBGA
 (as viewed from top through the package)
 (1 of 4)

⁴ "FM on" = FM depth of $\pm 2\%$ ⁵ K = 30 dB μ V**Table 8. EMC Radiated Emissions Operating Behaviors: 516 BGA**

Symbol	Description	Conditions	f _{osc} f _{SYS}	Frequency band (MHz)	Level (max.)	Unit	Notes
V _{RE_TEM}	Radiated emissions, electric field and magnetic field	V _{DD} = 1.2 V V _{DDE} = 3.3 V V _{DDEH} = 5 V T _A = 25 °C 516 BGA EBI on CLK on FM off	40 MHz crystal 264 MHz (f _{EBI_CAL} = 66 MHz)	0.15–50	40	dB μ V	¹
				50–150	48		
				150–500	48		
				500–1000	47		
				IEC and SAE level	G ²		^{1, 3}
V _{RE_TEM}	Radiated emissions, electric field and magnetic field	V _{DD} = 1.2 V V _{DDE} = 3.3 V V _{DDEH} = 5 V T _A = 25 °C 516 BGA EBI on CLK on FM on ⁴	40 MHz crystal 264 MHz (f _{EBI_CAL} = 66 MHz)	0.15–50	40	dB μ V	¹
				50–150	44		
				150–500	41		
				500–1000	36		
				IEC and SAE level	G ²		^{1, 3}

¹ Determined according to IEC Standard 61967-2, Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method, and SAE Standard J1752-3, Measurement of Radiated Emissions from Integrated Circuits—TEM/Wideband TEM (GTEM) Cell Method.

² G = 48 dB μ V

³ Specified according to Annex D of IEC Standard 61967-2, Measurement of Radiated Emissions—TEM Cell and Wideband TEM Cell Method, and Appendix D of SAE Standard J1752-3, Measurement of Radiated Emissions from Integrated Circuits—TEM/Wideband TEM (GTEM) Cell Method.

⁴ "FM on" = FM depth of $\pm 2\%$

4.4 ESD Characteristics

Table 9. ESD Ratings^{1,2}

Spec	Characteristic	Symbol	Value	Unit
1	ESD for Human Body Model (HBM)	V _{HBM}	2000	V
2	ESD for Charged Device Model (CDM)	V _{CDM}	750 (corners) 500 (other)	V

¹ All ESD testing is in conformity with CDF-AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits.

² A device will be defined as a failure if after exposure to ESD pulses the device no longer meets the device specification requirements. Complete DC parametric and functional testing shall be performed per applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

4.5 PMC/POR/LVI Electrical Specifications

Note: For ADC internal resource measurements, see Table 21 in Section 4.9.1, "ADC Internal Resource Measurements."

Electrical Characteristics

Table 14. DC Electrical Specifications (continued)

Spec	Characteristic	Symbol	Min	Max	Unit
27	Operating Current V_{DDE}/V_{DDEH} ¹⁷ Supplies V_{DDE2} V_{DDEH1} V_{DDEH3} V_{DDEH4} V_{DDEH5} V_{DDEH6} V_{DDEH7}	I_{DD2} I_{DD1} I_{DD3} I_{DD4} I_{DD5} I_{DD6} I_{DD7}	— — — — — — —	note ¹⁷	mA mA mA mA mA mA mA
28	Fast I/O Weak Pull Up/Down Current ¹⁸ 3.0 V–3.6 V	I_{ACT_F}	42	158	μA
29	Medium I/O Weak Pull Up/Down Current ¹⁹ 3.0 V–3.6 V 4.5 V–5.5 V	I_{ACT_S}	15 35	95 200	μA μA
30	I/O Input Leakage Current ²⁰	I_{INACT_D}	-2.5	2.5	μA
31	DC Injection Current (per pin)	I_{IC}	-1.0	1.0	mA
32	Analog Input Current, Channel Off ²¹ , AN[0:7], AN38, AN39 Analog Input Current, Channel Off, all other analog inputs AN[x]	I_{INACT_A}	-250 -150	250 150	nA nA
33	V_{SS} Differential Voltage	$V_{SS} - V_{SSA}$	-100	100	mV
34	Analog Reference Low Voltage	V_{RL}	V_{SSA}	$V_{SSA} + 100$	mV
35	V_{RL} Differential Voltage	$V_{RL} - V_{SSA}$	-100	100	mV
36	Analog Reference High Voltage	V_{RH}	$V_{DDA} - 100$	V_{DDA}	mV
37	V_{REF} Differential Voltage	$V_{RH} - V_{RL}$	4.75	5.25	V
38	V_{SSSYN} to V_{SS} Differential Voltage	$V_{SSSYN} - V_{SS}$	-100	100	mV
39	Operating Temperature Range—Ambient (Packaged)	T_A (T_L to T_H)	-40.0	125.0	°C
40	Slew rate on power supply pins	—	—	25	V/ms
41	Weak Pull-Up/Down Resistance ²² , 200 K Option	$R_{PUPD200K}$	130	280	kΩ
42	Weak Pull-Up/Down Resistance ²² , 100 K Option	$R_{PUPD100K}$	65	140	kΩ
43	Weak Pull-Up/Down Resistance ²² , 5 K Option	R_{PUPD5K}	1.4	7.5	kΩ
44	Pull-Up/Down Resistance Matching Ratios ²³ (100K/200K)	$R_{PUPDMTCH}$	-2.5	+2.5	%

¹ Voltage overshoots during a high-to-low or low-to-high transition must not exceed 10 seconds per instance.

² 2.0 V for 10 hours cumulative time, 1.2 V +10% for time remaining.

³ Assumed with DC load.

⁴ 5.3 V for 10 hours cumulative time, 3.3 V +10% for time remaining.

⁵ 6.4 V for 10 hours cumulative time, 5.0 V +10% for time remaining.

⁶ V_{STBY} below 0.95 V the RAM will not retain states, but will be operational. V_{STBY} can be 0 V when bypass standby mode.

⁷ Regulator is functional with derated performance, with supply voltage down to 4.0 V for system with $V_{DDREG} = 4.5$ V (min).

⁸ 2.7 V minimum operating voltage allowed during vehicle crank for system with $V_{DDREG} = 3.0$ V (min). Normal operating voltage should be either $V_{DDREG} = 3.0$ V (min) or 4.5 V (min) depending on the user regulation voltage system selected.

⁹ Required to be supplied when 3.3 V regulator is disabled. See Section 4.5, “PMC/POR/LVI Electrical Specifications.”

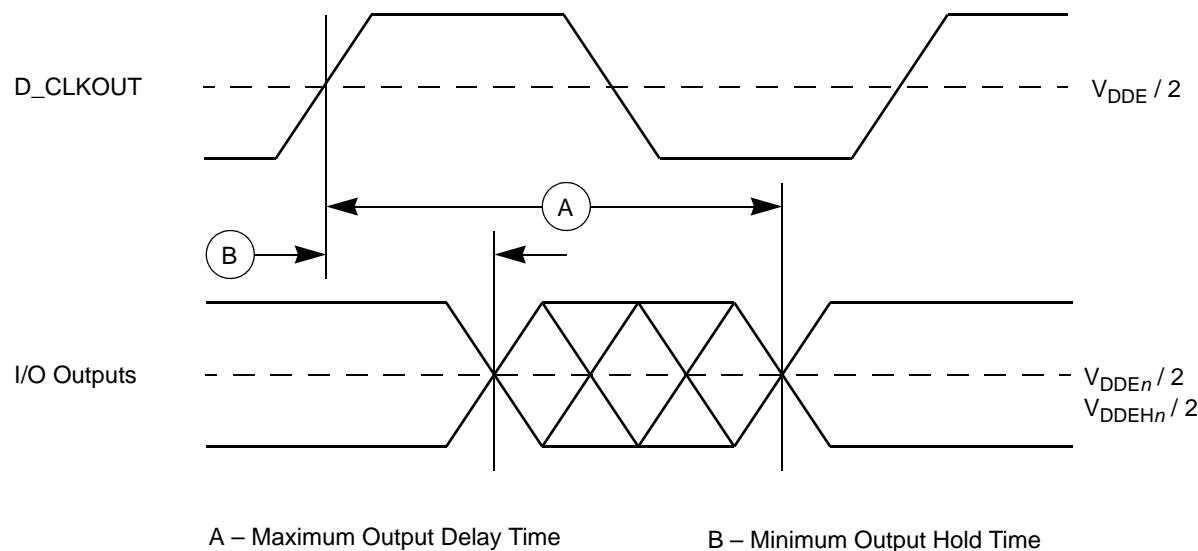


Figure 18. Generic Output Delay/Hold Timing

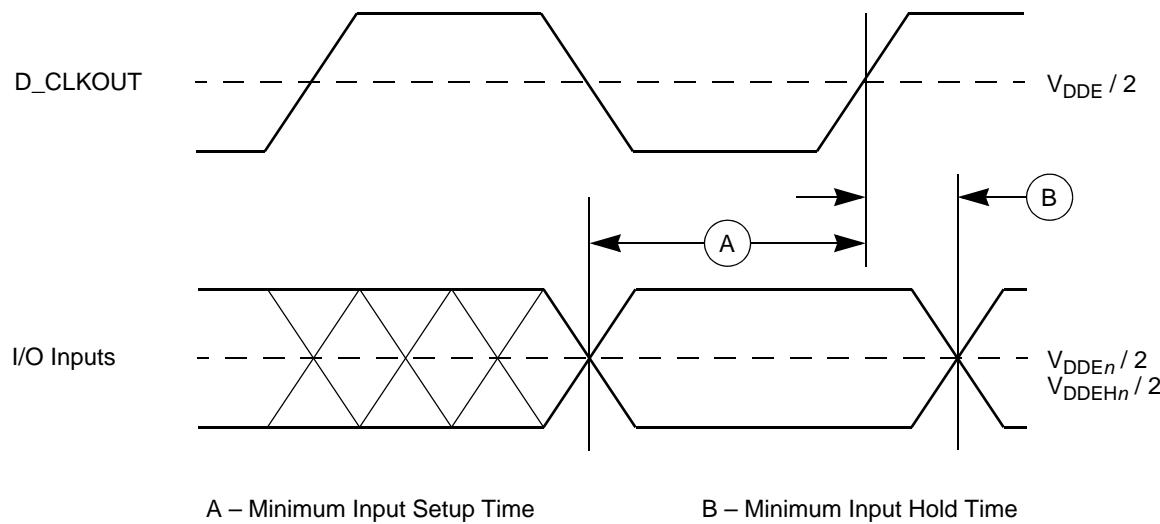


Figure 19. Generic Input Setup/Hold Timing

4.12.2 Reset and Configuration Pin Timing

Table 33. Reset and Configuration Pin Timing¹

Spec	Characteristic	Symbol	Min	Max	Unit
1	RESET Pulse Width	t_{RPW}	10	—	t_{cyc}^2
2	RESET Glitch Detect Pulse Width	t_{GPW}	2	—	t_{cyc}^2
3	PLLCFG, BOOTCFG, WKPCFG Setup Time to RSTOUT Valid	t_{RCSU}	10	—	t_{cyc}^2
4	PLLCFG, BOOTCFG, WKPCFG Hold Time to RSTOUT Valid	t_{RCH}	0	—	t_{cyc}^2

¹ Reset timing specified at: $V_{DDEH} = 3.0 \text{ V to } 5.25 \text{ V}$, $V_{DD} = 1.08 \text{ V to } 1.32 \text{ V}$, $T_A = T_L$ to T_H .

Electrical Characteristics

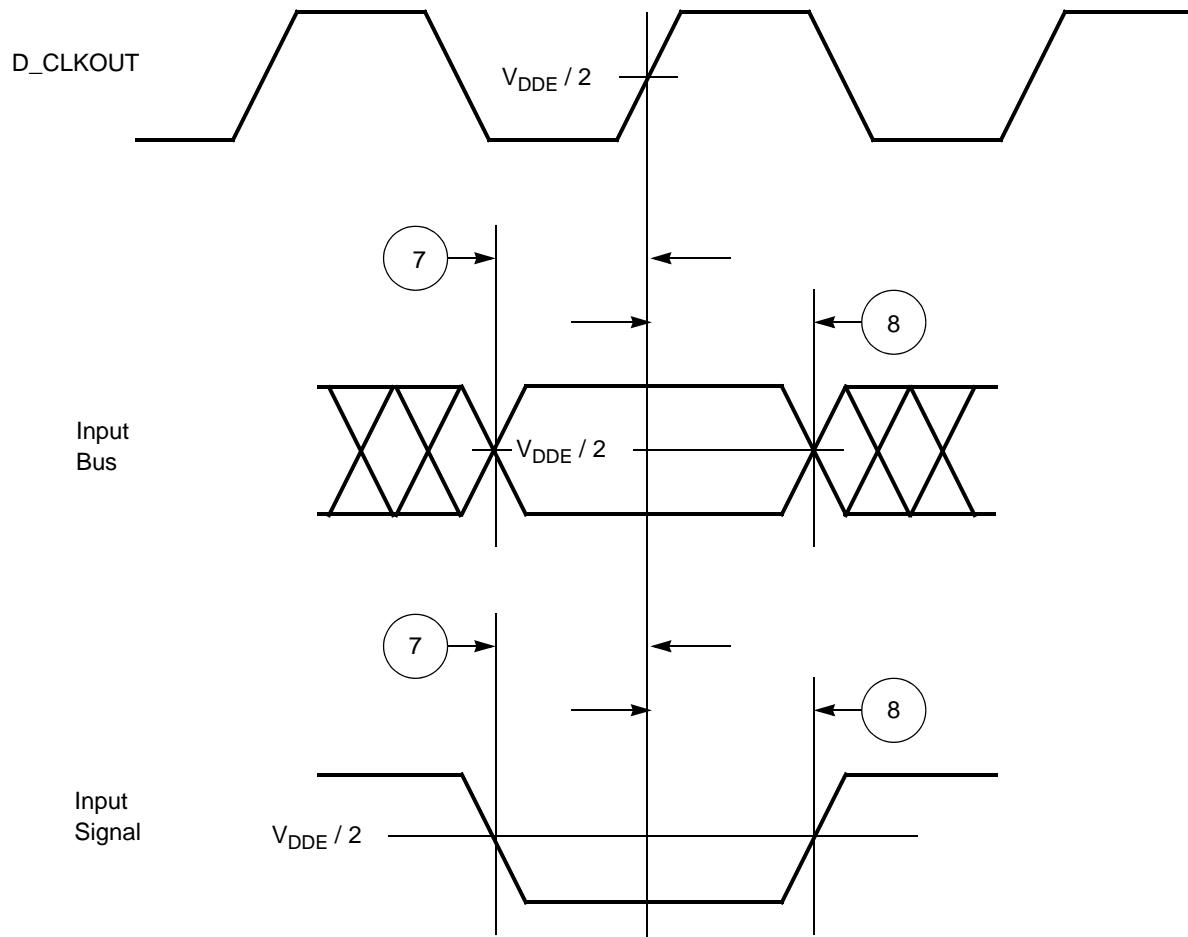


Figure 29. Synchronous Input Timing

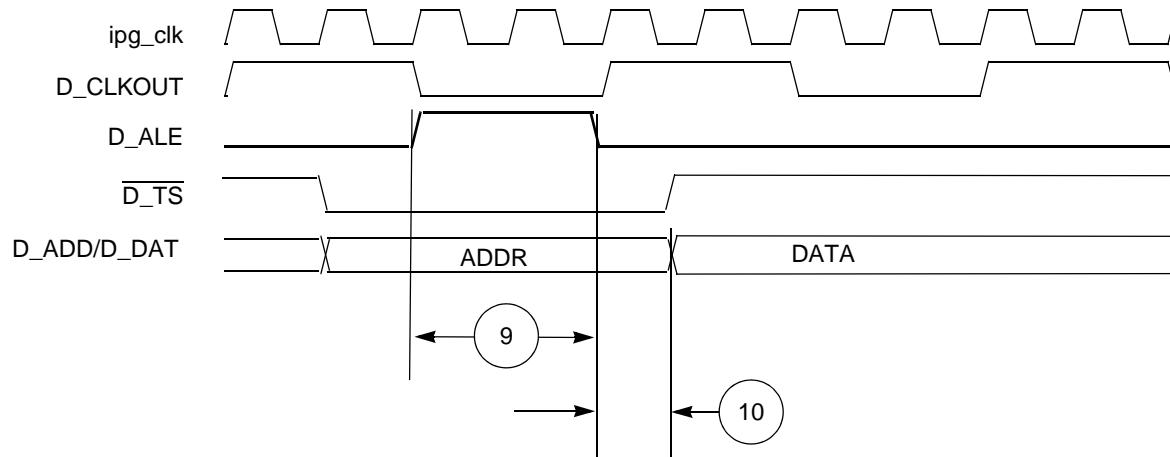


Figure 30. ALE Signal Timing

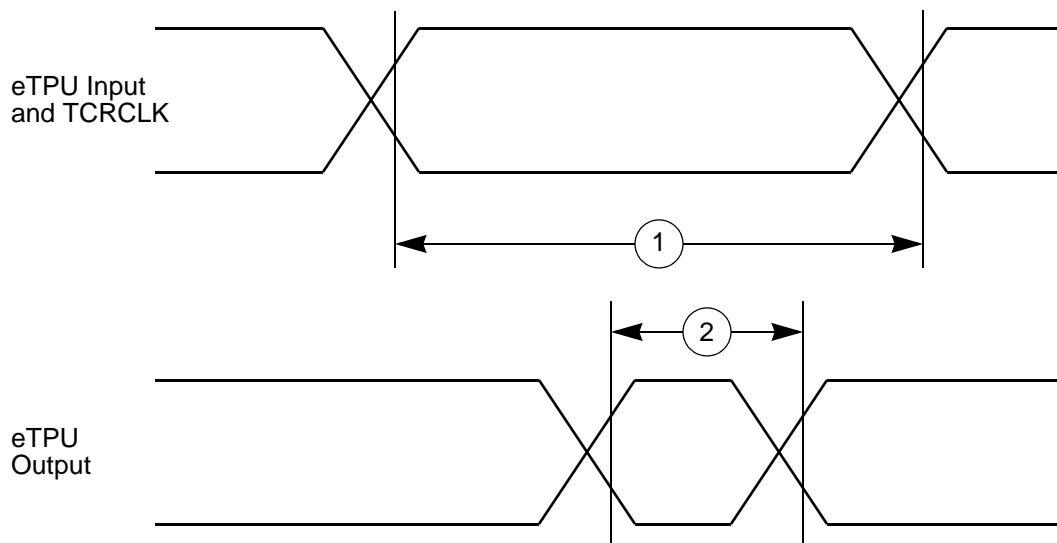


Figure 32. eTPU Timing

4.12.8 eMIOS Timing

Table 39. eMIOS Timing¹

Spec	Characteristic	Symbol	Min	Max	Unit
1	eMIOS Input Pulse Width	t_{MIPW}	4	—	t_{cyc}^2
2	eMIOS Output Pulse Width	t_{MOPW}	1 ³	—	t_{cyc}^2

¹ eMIOS timing specified at $V_{DD} = 1.08\text{ V}$ to 1.32 V , $V_{DDEH} = 3.0\text{ V}$ to 5.5 V , V_{DD33} and $V_{DDSYN} = 3.0\text{ V}$ to 3.6 V , $T_A = T_L$ to T_H , and $C_L = 50\text{ pF}$ with SRC = 0b00.

² See Notes on t_{cyc} on Figure 16 and Table 28 in Section 4.11.1 Clocking.

³ This specification does not include the rise and fall times. When calculating the minimum eMIOS pulse width, include the rise and fall times defined in the slew rate control fields (SRC) of the pad configuration registers (PCR).

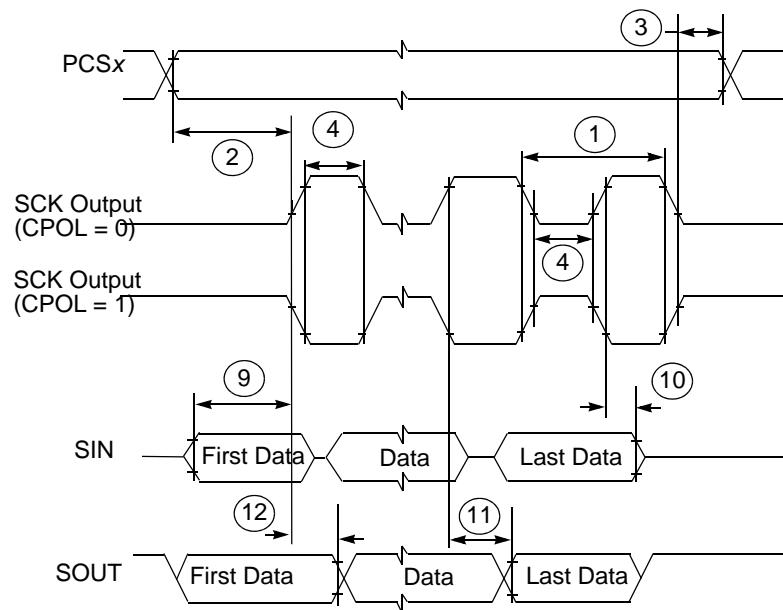


Figure 38. DSPI Modified Transfer Format Timing — Master, CPHA = 0

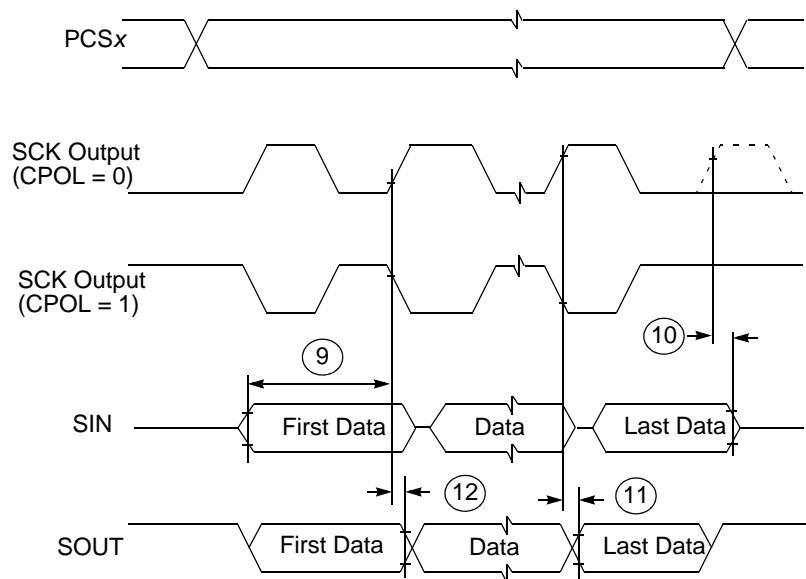


Figure 39. DSPI Modified Transfer Format Timing — Master, CPHA = 1

Table 43. Signal Properties and Muxing Summary

Table 43. Signal Properties and Muxing Summary (continued)

GPIO/PCR ¹	Signal Name ²	P/A/G ³	Function ⁴	Function Summary	Direction	Pad Type ⁵	Voltage ⁶	State during RESET ⁷	State after RESET ⁸	Package Location		
										324	416	516
161	ETPUB14_ETPUB30_GPIO161	P	ETPUB14	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	L21	M25	R24
		A1	ETPUB30	eTPU B channel (output only)	O							
		A2	—	—	—							
		G	GPIO161	GPIO	I/O							
162	ETPUB15_ETPUB31_GPIO162	P	ETPUB15	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	—	M24	R25
		A1	ETPUB31	eTPU B channel (output only)	O							
		A2	—	—	—							
		G	GPIO162	GPIO	I/O							
163	ETPUB16_PCSA1_GPIO163	P	ETPUB16	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	P20	U26	V24
		A1	PCSA1	DSPI A peripheral chip select	O							
		A2	—	—	—							
		G	GPIO163	GPIO	I/O							
164	ETPUB17_PCSA2_GPIO164	P	ETPUB17	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	R20	U25	T21
		A1	PCSA2	DSPI A peripheral chip select	O							
		A2	—	—	—							
		G	GPIO164	GPIO	I/O							
165	ETPUB18_PCSA3_GPIO165	P	ETPUB18	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	T20	U24	W26
		A1	PCSA3	DSPI A peripheral chip select	O							
		A2	—	—	—							
		G	GPIO165	GPIO	I/O							
166	ETPUB19_PCSA4_GPIO166	P	ETPUB19	eTPU B channel	I/O	MH	V _{DDEH6}	—/WKPCFG	—/WKPCFG	T19	U23	W25
		A1	PCSA4	DSPI A peripheral chip select	O							
		A2	—	—	—							
		G	GPIO166	GPIO	I/O							

Table 43. Signal Properties and Muxing Summary (continued)

GPIO/PCR ¹	Signal Name ²	P/A/G ³	Function ⁴	Function Summary	Direction	Pad Type ⁵	Voltage ⁶	State during RESET ⁷	State after RESET ⁸	Package Location		
										324	416	516
433	EMIOS27_PCSB3_GPIO433	P	EMIOS27	eMIOS channel	I/O	MH	V _{DDEH4}	—/WKPCFG	—/WKPCFG	W14	AC17	AD18
		A1	PCSB3	DSPI B peripheral chip select	O							
		A2	—	—	—							
		G	GPIO433	GPIO	I/O							
434	EMIOS28_PCSC0_GPIO434	P	EMIOS28	eMIOS channel	I/O	MH	V _{DDEH4}	—/WKPCFG	—/WKPCFG	AA16	AF18	AC18
		A1	PCSC0	DSPI C peripheral chip select	I/O							
		A2	—	—	—							
		G	GPIO434	GPIO	I/O							
435	EMIOS29_PCSC1_GPIO435	P	EMIOS29	eMIOS channel	I/O	MH	V _{DDEH4}	—/WKPCFG	—/WKPCFG	AA17	AE18	AB17
		A1	PCSC1	DSPI C peripheral chip select	O							
		A2	—	—	—							
		G	GPIO435	GPIO	I/O							
436	EMIOS30_PCSC2_GPIO436	P	EMIOS30	eMIOS channel	I/O	MH	V _{DDEH4}	—/WKPCFG	—/WKPCFG	Y17	AD18	AF19
		A1	PCSC2	DSPI C peripheral chip select	O							
		A2	—	—	—							
		G	GPIO436	GPIO	I/O							
437	EMIOS31_PCSC5_GPIO437	P	EMIOS31	eMIOS channel	I/O	MH	V _{DDEH4}	—/WKPCFG	—/WKPCFG	W15	AC18	AA17
		A1	PCSC5	DSPI C peripheral chip select	O							
		A2	—	—	—							
		G	GPIO437	GPIO	I/O							
eQADC												
—	ANA0	P	ANA0 ¹⁰	eQADC A analog input	I	AE/up-down	V _{DDA_A1}	ANA0	ANA0	A4	A4	A4
—	ANA1	P	ANA1 ¹⁰	eQADC A analog input	I	AE/up-down	V _{DDA_A1}	ANA1	ANA1	A5	B5	B5
—	ANA2	P	ANA2 ¹⁰	eQADC A analog input	I	AE/up-down	V _{DDA_A1}	ANA2	ANA2	B5	C5	C5

Table 43. Signal Properties and Muxing Summary (continued)

GPIO/PCI ¹	Signal Name ²	P/A/G ³	Function ⁴	Function Summary	Direction	Pad Type ⁵	Voltage ⁶	State during RESET ⁷	State after RESET ⁸	Package Location		
										324	416	516
—	AN27	P	AN27	eQADC A and B shared analog input	I	AE	V _{DDA_A0}	AN27	AN27	—	B13	B13
—	AN28	P	AN28	eQADC A and B shared analog input	I	AE	V _{DDA_A0}	AN28	AN28	—	A13	A13
—	AN29	P	AN29	eQADC A and B shared analog input	I	AE	V _{DDA_A0}	AN29	AN29	—	B14	A14
—	AN30	P	AN30	eQADC A and B shared analog input	I	AE	V _{DDA_B1}	AN30	AN30	—	C14	B14
—	AN31	P	AN31	eQADC A and B shared analog input	I	AE	V _{DDA_B1}	AN31	AN31	—	D14	C14
—	AN32	P	AN32	eQADC A and B shared analog input	I	AE	V _{DDA_B1}	AN32	AN32	—	A14	B15
—	AN33	P	AN33	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN33	AN33	—	B15	D14
—	AN34	P	AN34	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN34	AN34	—	C15	C15
—	AN35	P	AN35	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN35	AN35	—	D15	D15
—	AN36	P	AN36	eQADC A and B shared analog input	I	AE	V _{DDA_B1}	AN36	AN36	—	A15	A15
—	AN37	P	AN37	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN37	AN37	—	C16	C17
—	AN38	P	AN38	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN38	AN38	—	C17	D16
—	AN39	P	AN39	eQADC A and B shared analog input	I	AE	V _{DDA_B0}	AN39	AN39	—	D16	C16
—	ANB0	P	ANB0	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB0	ANB0	B15	C18	C18
—	ANB1	P	ANB1	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB1	ANB1	B16	D17	D17
—	ANB2	P	ANB2	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB2	ANB2	A17	D18	D18
—	ANB3	P	ANB3	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB3	ANB3	A18	D19	D19
—	ANB4	P	ANB4	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB4	ANB4	B17	C19	B19
—	ANB5	P	ANB5	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB5	ANB5	B18	C20	A20
—	ANB6	P	ANB6	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB6	ANB6	A19	B19	C20
—	ANB7	P	ANB7	eQADC B analog input	I	AE/up-down	V _{DDA_B0}	ANB7	ANB7	A20	A20	C19
—	ANB8	P	ANB8	eQADC B analog input	I	AE	V _{DDA_B0}	ANB8	ANB8	D13	B20	B20

Table 43. Signal Properties and Muxing Summary (continued)

GPIO/PCR ¹	Signal Name ²	P/A/G ³	Function ⁴	Function Summary	Direction	Pad Type ⁵	Voltage ⁶	State during RESET ⁷	State after RESET ⁸	Package Location		
										324	416	516
—	ANB9	P	ANB9	eQADC B analog input	I	AE	V _{DDA_B0}	ANB9	ANB9	C14	D20	A21
—	ANB10	P	ANB10	eQADC B analog input	I	AE	V _{DDA_B0}	ANB10	ANB10	C13	B21	B21
—	ANB11	P	ANB11	eQADC B analog input	I	AE	V _{DDA_B0}	ANB11	ANB11	C15	A21	C21
—	ANB12	P	ANB12	eQADC B analog input	I	AE	V _{DDA_B0}	ANB12	ANB12	C16	C21	A22
—	ANB13	P	ANB13	eQADC B analog input	I	AE	V _{DDA_B0}	ANB13	ANB13	D14	D21	B22
—	ANB14	P	ANB14	eQADC B analog input	I	AE	V _{DDA_B0}	ANB14	ANB14	C17	A22	D20
—	ANB15	P	ANB15	eQADC B analog input	I	AE	V _{DDA_B0}	ANB15	ANB15	D15	B22	C22
—	ANB16	P	ANB16	eQADC B analog input	I	AE	V _{DDA_B0}	ANB16	ANB16	C18	C22	D21
—	ANB17	P	ANB17	eQADC B analog input	I	AE	V _{DDA_B0}	ANB17	ANB17	D16	A23	D22
—	ANB18	P	ANB18	eQADC B analog input	I	AE	V _{DDA_B0}	ANB18	ANB18	D17	B23	A23
—	ANB19	P	ANB19	eQADC B analog input	I	AE	V _{DDA_B0}	ANB19	ANB19	B19	C23	B23
—	ANB20	P	ANB20	eQADC B analog input	I	AE	V _{DDA_B0}	ANB20	ANB20	C19	D22	C23
—	ANB21	P	ANB21	eQADC B analog input	I	AE	V _{DDA_B0}	ANB21	ANB21	D18	A24	A24
—	ANB22	P	ANB22	eQADC B analog input	I	AE	V _{DDA_B0}	ANB22	ANB22	A21	B24	B24
—	ANB23	P	ANB23	eQADC B analog input	I	AE	V _{DDA_B0}	ANB23	ANB23	B20	A25	E20
—	VRH_A	P	VRH_A	ADC A Voltage reference high	I	VDDINT	V _{RH_A}	VRH_A	VRH_A	A10	A12	A12
—	VRL_A	P	VRL_A	ADC A Voltage reference low	I	VSSINT	V _{RL_A}	VRL_A	VRL_A	A11	A11	A11
—	VRH_B	P	VRH_B	ADC B Voltage reference high	I	VDDINT	V _{RH_B}	VRH_B	VRH_B	A16	A19	A19
—	VRL_B	P	VRL_B	ADC B Voltage reference low	I	VSSINT	V _{RL_B}	VRL_B	VRL_B	A15	A18	A18
—	REFBYPCB	P	REFBYPCB	ADC B Reference bypass capacitor	I	AE	V _{DDA_B0}	REFBYPCB	REFBYPCB	B12	B18	B18
—	REFBYPCA	P	REFBYPCA	ADC A Reference bypass capacitor	I	AE	V _{DDA_A1}	REFBYPCA	REFBYPCA	B11	B11	B11
—	VDDA_A0	P	VDDA_A	Internal logic supply input	I	VDDE	V _{DDA_A0}	VDDA_A0	VDDA_A0	A9	A9	A9
—	VDDA_A1	P	VDDA_A	Internal logic supply input	I	VDDE	V _{DDA_A1}	VDDA_A1	VDDA_A1	B9	B9	B9
—	REFBYPCA1	P	REFBYPCA1	ADC A Reference bypass capacitor	I	AE	V _{DDA_A1}	REFBYPCA1	REFBYPCA1	A12	A10	A10
—	VSSA_A1	P	VSSA_A	Ground	I	VSSE	V _{SSA_A1}	VSSA_A1	VSSA_A1	B10	B10	B10
—	VDDA_B0	P	VDDA_B	Internal logic supply input	I	VDDE	V _{DDA_B0}	VDDA_B0	VDDA_B0	A13	A16	A16
—	VDDA_B1	P	VDDA_B	Internal logic supply input	I	VDDE	V _{DDA_B1}	VDDA_B1	VDDA_B1	B13	B16	B16

Table 43. Signal Properties and Muxing Summary (continued)

GPIO/PCI ¹	Signal Name ²	P/A/G ³	Function ⁴	Function Summary	Direction	Pad Type ⁵	Voltage ⁶	State during RESET ⁷	State after RESET ⁸	Package Location		
										324	416	516
278	D_ADD_DAT0_GPIO278	P	D_ADD_DAT0	EBI data only in non-mux mode. Address and data in mux mode.	I/O	F	V _{DDE10}	—/Up	—/Up	—	—	P25
		A1	—	—	—							
		A2	—	—	—							
		G	GPIO278	GPIO	I/O							
279	D_ADD_DAT1_GPIO279	P	D_ADD_DAT1	EBI data only in non-mux mode. Address and data in mux mode.	I/O	F	V _{DDE10}	—/Up	—/Up	—	—	P26
		A1	—	—	—							
		A2	—	—	—							
		G	GPIO279	GPIO	I/O							
280	D_ADD_DAT2_GPIO280	P	D_ADD_DAT2	EBI data only in non-mux mode. Address and data in mux mode.	I/O	F	V _{DDE10}	—/Up	—/Up	—	—	N24
		A1	—	—	—							
		A2	—	—	—							
		G	GPIO280	GPIO	I/O							
281	D_ADD_DAT3_GPIO281	P	D_ADD_DAT3	EBI data only in non-mux mode. Address and data in mux mode.	I/O	F	V _{DDE10}	—/Up	—/Up	—	—	N25
		A1	—	—	—							
		A2	—	—	—							
		G	GPIO281	GPIO	I/O							
282	D_ADD_DAT4_GPIO282	P	D_ADD_DAT4	EBI data only in non-mux mode. Address and data in mux mode.	I/O	F	V _{DDE10}	—/Up	—/Up	—	—	N26
		A1	—	—	—							
		A2	—	—	—							
		G	GPIO282	GPIO	I/O							

Table 43. Signal Properties and Muxing Summary (continued)